

METHOD OF MANUFACTURING CHIP

ABSTRACT

A method of manufacturing an optionally shaped chip from a substrate having a crystalline structure includes a projected dicing line establishing step of establishing on the substrate a contour of a chip to be fabricated from the substrate and a straight division assisting line contacting the contour of the chip for assisting in dividing the substrate, a division initiating point forming step of, after the projected dicing line establishing step, applying a laser beam having a wavelength transmittable through the substrate to the substrate along the contour of the chip and the division assisting line while positioning a focused spot of the laser beam in the substrate at a predetermined position spaced from an upper surface of the substrate, thereby forming division initiating points in the substrate, and a dividing step of applying external forces to the substrate in which the division initiating points have been formed, to divide the substrate along the division initiating points.

[Fig. 1]